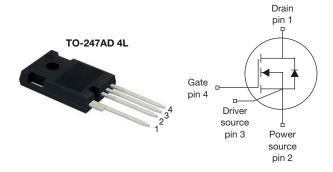
Vishay Siliconix

COMPLIANT

HALOGEN

FREE

E Series Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V 0.020			
Q _g max. (nC)	225			
Q _{gs} (nC)	73			
Q _{gd} (nC)	31			
Configuration	Single			

FEATURES

- 4th generation E series technology
- ullet Low figure-of-merit (FOM) $R_{on} \times Q_g$
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-247AD 4L
Lead (Pb)-free and halogen-free	SiHL023N60E-GE3

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	600	V
Gate-source voltage			V_{GS}	± 30	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Continuous drain current (T _{.I} = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I _D	96	А
Continuous drain current (1) = 150 °C)	V _{GS} at 10 V	T _C = 100 °C		61	
Pulsed drain current ^a			I _{DM}	326	
Linear derating factor				4.2	W/°C
Single pulse avalanche energy b			E _{AS}	1019	mJ
Maximum power dissipation			P_{D}	521	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope		dv/dt	100	1//20	
Reverse diode dv/dt ^d			100	- V/ns	
Soldering recommendations (peak temperature) c For 10 s			260	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 8.5 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting $T_J = 25$ °C



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	=	40	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	-	0.24	C/VV	

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.64	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	V _{GS} , I _D = 250 μA	3	-	5	V
0.1		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
7		V _{DS} =	V _{DS} = 600 V, V _{GS} = 0 V		-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 38 A	-	0.020	0.023	Ω
Forward transconductance	9 _{fs}	V _{DS}	= 50 V, I _D = 38 A	-	22	-	S
Dynamic							
Input capacitance	C _{iss}		$V_{GS} = 0 \text{ V}, $ $V_{DS} = 100 \text{ V},$		10 291	-	pF
Output capacitance	C _{oss}	,			314	-	
Reverse transfer capacitance	C _{rss}	f = 60 KHz		-	3	-	
Effective output capacitance, energy related	C _{o(er)}	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	385	-	
Effective output capacitance, time related	C _{o(tr)}			-	2449	-	
Total gate charge	Qg			-	150	225	
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 38 \text{ A}, V_{DS} = 480 \text{ V}$		73	-	nC
Gate-drain charge	Q _{gd}			-	31	-	1
Turn-on delay time	t _{d(on)}	$V_{DD} = 480 \text{ V}, I_{D} = 38 \text{ A}, V_{GS} = 10 \text{ V}, R_{g} = 10.1 \Omega$		-	97	146	
Rise time	t _r			-	32	64	
Turn-off delay time	t _{d(off)}			-	150	225	- ns
Fall time	t _f			-	5	6	
Gate input resistance	R_g	f = 1 MHz, open drain		0.5	1	2	Ω
Drain-Source Body Diode Characteristic	S						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	96	_
Pulsed diode forward current	I _{SM}			-	-	326	- A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 38 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 38 \text{A},$ $di/dt = 100 \text{A/µs}, V_R = 400 \text{V}$		-	590	1180	ns
Reverse recovery charge	Q _{rr}			-	10	20	μC
Reverse recovery current	I _{RRM}			-	28	-	A



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

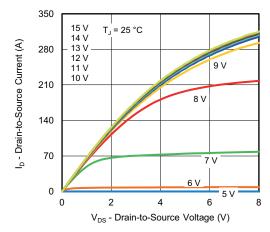


Fig. 1 - Typical Output Characteristics

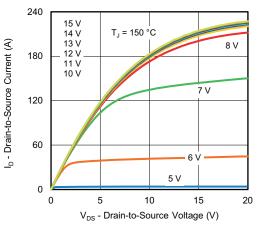


Fig. 2 - Typical Output Characteristics

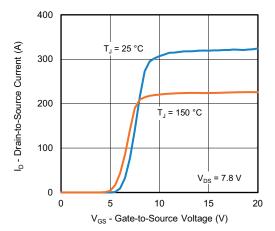


Fig. 3 - Typical Transfer Characteristics

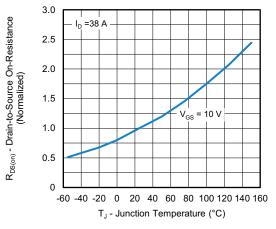


Fig. 4 - Normalized On-Resistance vs. Temperature

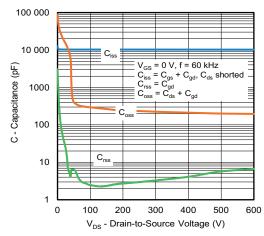


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

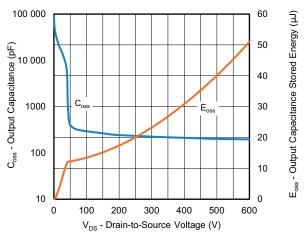


Fig. 6 - Coss and Eoss vs. VDS



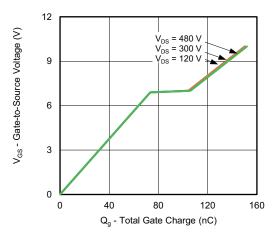


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

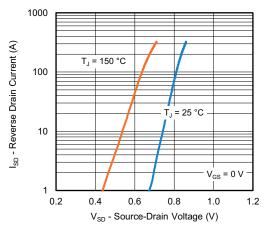


Fig. 8 - Typical Source-Drain Diode Forward Voltage

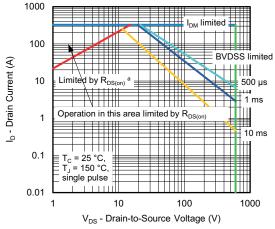


Fig. 9 - Maximum Safe Operating Area



a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

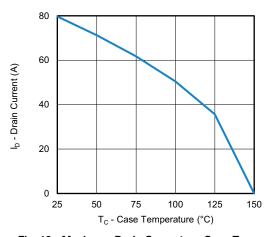


Fig. 10 - Maximum Drain Current vs. Case Temperature

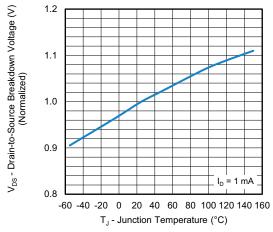


Fig. 11 - Temperature vs. Drain-to-Source Voltage



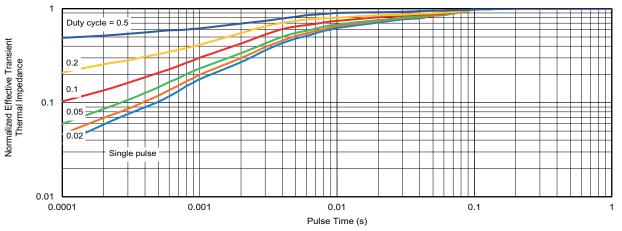


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

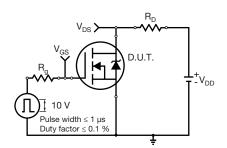


Fig. 13 - Switching Time Test Circuit

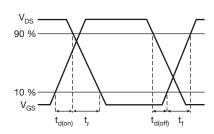


Fig. 14 - Switching Time Waveforms

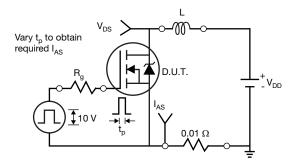


Fig. 15 - Unclamped Inductive Test Circuit

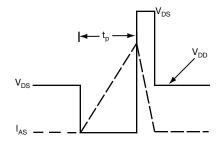


Fig. 16 - Unclamped Inductive Waveforms

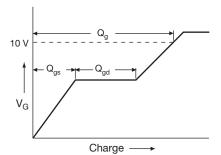


Fig. 17 - Basic Gate Charge Waveform

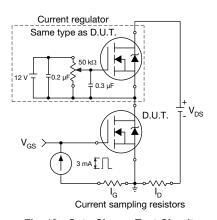
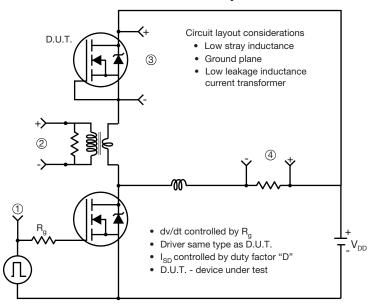


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



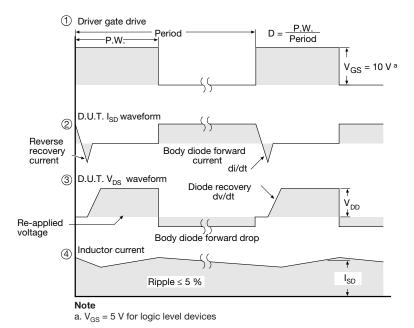


Fig. 19 - For N-Channel

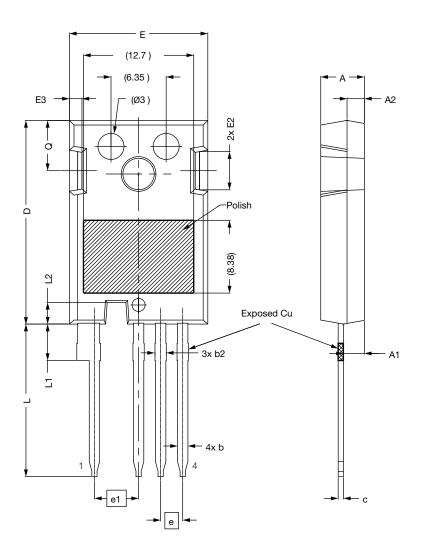
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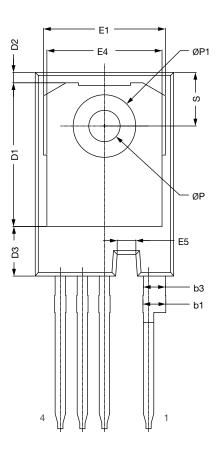


Vishay MaxPower Semiconductor

Case Outline for TO-247AD 4L Package

FACILITY CODE: 9







Package Information

www.vishay.com

Vishay MaxPower Semiconductor

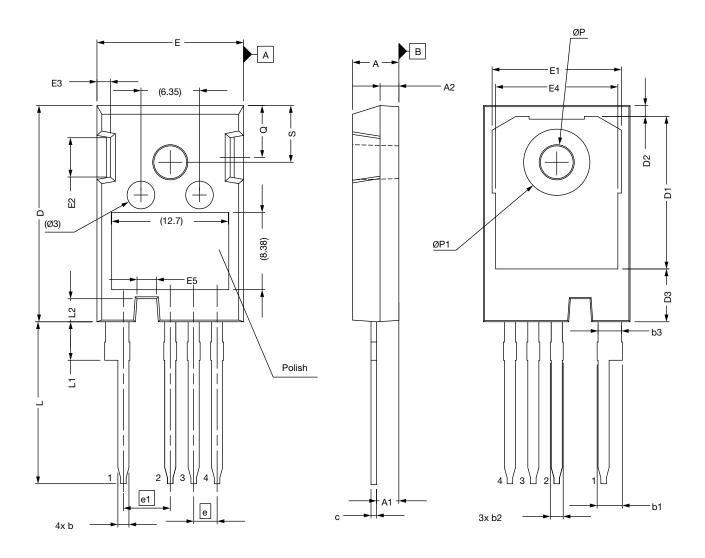
DIM.	MILLIMETERS		
DIWI.	MIN.	MAX.	
A	4.83	5.21	
A1	2.29	2.54	
A2	1.91	2.16	
b	1.07	1.33	
b1	2.39	2.94	
b3	1.07	1.60	
С	0.55	0.68	
D	23.30	23.60	
D1	16.25	17.65	
D2	0.95	1.25	
E	15.75	16.13	
E1	13.10	14.15	
E2	3.68	5.10	
E3	1.00	1.90	
E4	12.38	13.43	
E5	1.95	2.35	
e	2.54 BSC.		
e1	5.08 BSC.		
L	17.31	17.82	
L1	3.97	4.37	
L2	2.35	2.65	
ØP	3.51	3.65	
Q	5.49	6.00	
S	6.04	6.30	

Notes

- All dimensions are in mm. Angles are in degrees
- Dimension D and E do not include mold flash
- All metal surfaces: tin plated, except area of cut
- Dimensioning and toleranceing confirm to ASME Y14.5M-1994
- Creepage 1 is 8.58 mm (ref.) which is the distance alongside the surface between drain (pin 1) and trough the notch towards source (pin 2). Creepage 2 is 7.95 mm (ref.) which is the distance from end of the copper slug on the backside of the package to either pin 2, pin 3 or pin 4

Vishay MaxPower Semiconductor

FACILITY CODE: N





Package Information

www.vishay.com

Vishay MaxPower Semiconductor

DIM.	MILLIMETERS				
DIM.	MIN.	NOM.	MAX.		
Α	4.83	5.02	5.21		
A1	2.29	2.41	2.54		
A2	1.91	2.00	2.16		
b	1.07	1.20	1.33		
b1	2.39	2.67	2.94		
b2	1.07	1.30	1.60		
b3	2.39	2.53	2.69		
С	0.55	0.60	0.68		
D	23.30	23.45	23.60		
D1	16.25	16.55	17.65		
D2	0.95	1.19	1.25		
D3	5.55	5.71	6.01		
Е	15.75	15.94	16.13		
E1	13.10	14.02	14.15		
E2	3.68	4.40	5.10		
E3	1.00	1.45	1.90		
E4	12.38	13.26	13.43		
E5	1.95	2.15	2.35		
е		2.54 BSC.			
e1		5.08 BSC.			
L	17.31	17.57	17.82		
L1	3.97	4.19	4.37		
L2	2.35	2.50	2.65		
ØP	3.51	3.61	3.65		
ØP1		7.19 ref.			
Q	5.49	5.79	6.00		
S	6.04	6.17	6.30		
FCN: \$25-0851-Rev. C. 18-Jul-202	- 5	1			

ECN: S25-0851-Rev. C, 18-Jul-2025

DWG: 6121

Notes

- All dimensions are in mm
- Dimension D and E do not include mold flash.
- Creepage 1 is 8.40 mm (ref.) which is the distance alongside the surface between drain (pin 1) and trough the notch towards source (pin 2). Creepage 2 is 7.70 mm (ref.) which is the distance from end of the copper slug on the backside of the package to either pin 2, pin 3 or pin 4



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